



XTMS60R160F

600V N-ch Planar MOSFET

Product Description

BV_{DSS}	600	V
I_D	20	A
$R_{DS(ON),Typ.}$	0.16	Ω

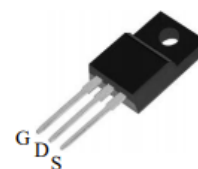
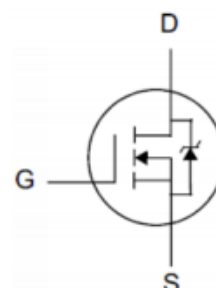
General Features

- RoHS Compliant
- $R_{DS(ON),typ.}=0.16\Omega@V_{GS}=10V$
- Fast Recovery Body Diode
- Low Gate Charge Minimize Switching Loss

Applications

- Adaptor
- Charger
- SMPS Standby Power

封装 Package



TO-220F

Device	Package	Marking
XTMS60R160F	TO-220F	XTMS60R160F

Absolute Maximum Ratings $T_j=25^\circ\text{C}$

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-to-Source Voltage	600	V
V_{GSS}	Gate-to-Source Voltage	± 30	
I_D	Continuous Drain Current	20	A
I_{DM}	Pulsed Drain Current at $V_{GS}=10V$	80	
E_{AS}	Single Pulse Avalanche Energy	663	mJ
P_D	Power Dissipation	45	W
	Derating Factor above 25°C	663	W/ $^\circ\text{C}$
$T_J \& T_{STG}$	Operating and Storage Temperature Range	-55 to 150	$^\circ\text{C}$

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

**Thermal Characteristics**

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2.8	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	$^{\circ}C/W$

Electrical Characteristics $T_j=25^{\circ}C$ **OFF Characteristics**

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
BV_{DSS}	Drain-to-Source Breakdown Voltage	600	-	-	V	$V_{GS}=0V, I_D=250\mu A$
I_{DSS}	Drain-to-Source Leakage Current	-	-	1.0	μA	$V_{DS}=600V, V_{GS}=0V$
		-	3.0	-		$V_{DS}=600V, V_{GS}=0V, T_j=125^{\circ}C$
I_{GSS}	Gate-to-Source Leakage Current	-	-	+100	nA	$V_{GS}=+30V, V_{DS}=0V$
		-	-	-100		$V_{GS}=-30V, V_{DS}=0V$

ON Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	-	0.16	0.19	Ω	$V_{GS}=10V, I_D=10A$
$V_{GS(TH)}$	Gate Threshold Voltage	2.0	-	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$



Dynamic Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
C_{iss}	Input Capacitance	-	1776	-	pF	$V_{GS}=0V,$ $V_{DS}=100V,$ $f=1.0MHz$
C_{rSS}	Reverse Transfer Capacitance	-	65	-		
C_{OSS}	Output Capacitance	-	1.2	-		
Q_g	Total Gate Charge	-	46	-	nC	$V_{DD}=480V,$ $I_D=20A, V_{GS}=10V$
Q_{gs}	Gate-to-Source Charge	-	15	-		
Q_{gd}	Gate-to-Drain (Miller) Charge	-	20	-		

Resistive Switching Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
$t_{d(ON)}$	Turn-on Delay Time	-	30	-	ns	$V_{DD}=3000V,$ $I_D=20A,$ $V_{GS}=10V$ $R_g=250\Omega$
t_{rise}	Rise Time	-	64	-		
$t_{d(OFF)}$	Turn-Off Delay Time	-	119	-		
t_{fall}	Fall Time	-	49	-		

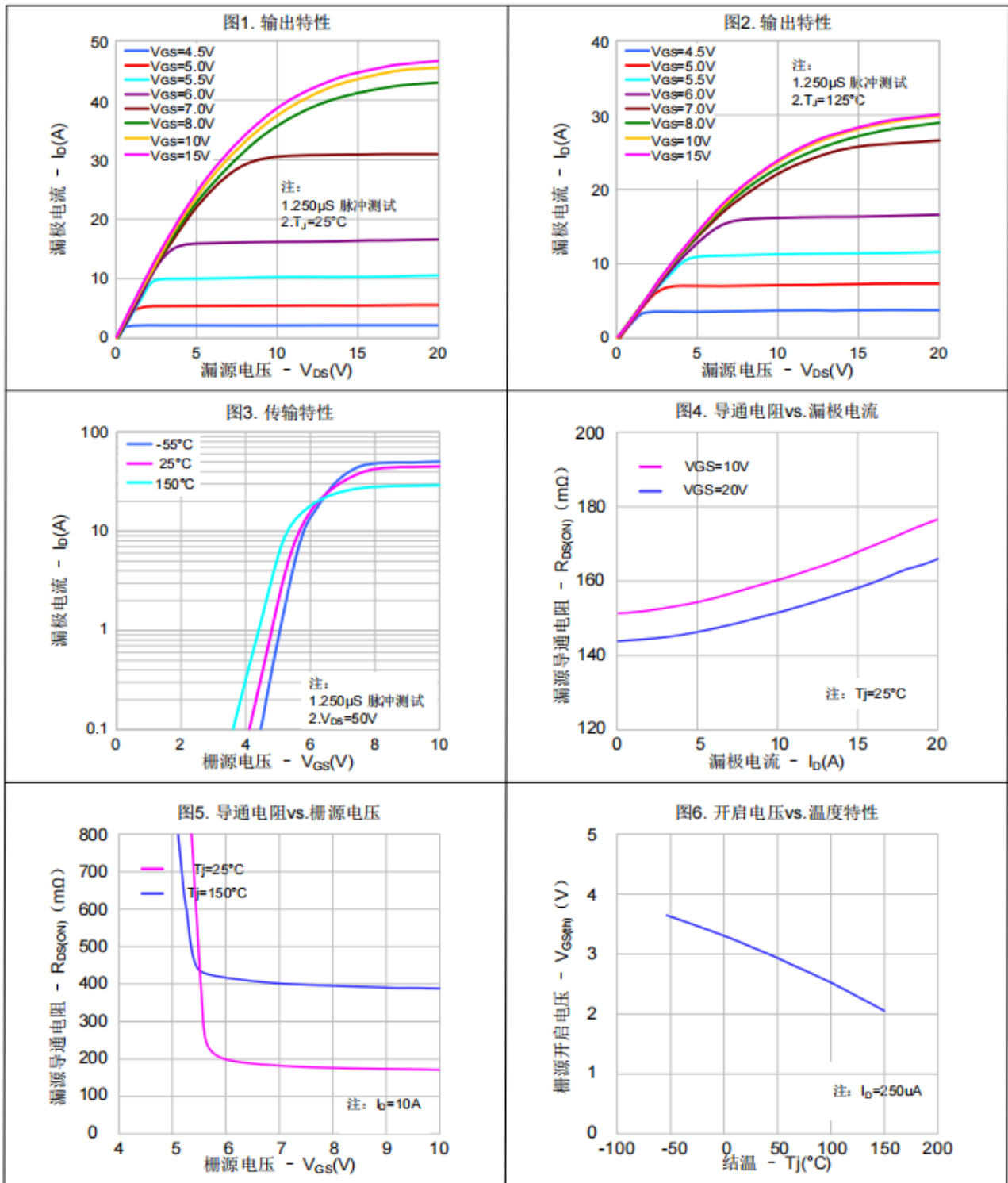
Source-Drain Body Diode Characteristics

Symbol	Parameter	Min	Typ	Max	Unit	Test Condition
V_{SD}	Diode Forward Voltage	-	-	1.4	V	$I_S=20A, V_{GS}=0V$
t_{rr}	Reverse Recovery Time	-	385	-	ns	$V_{GS}=0V I_S=20A,$ $di/dt=100A/\mu s$
Q_{rr}	Reverse Recovery Charge	-	5.8	-	uC	

[1] Pulse width $\leq 380\mu s$; duty cycle $\leq 2\%$

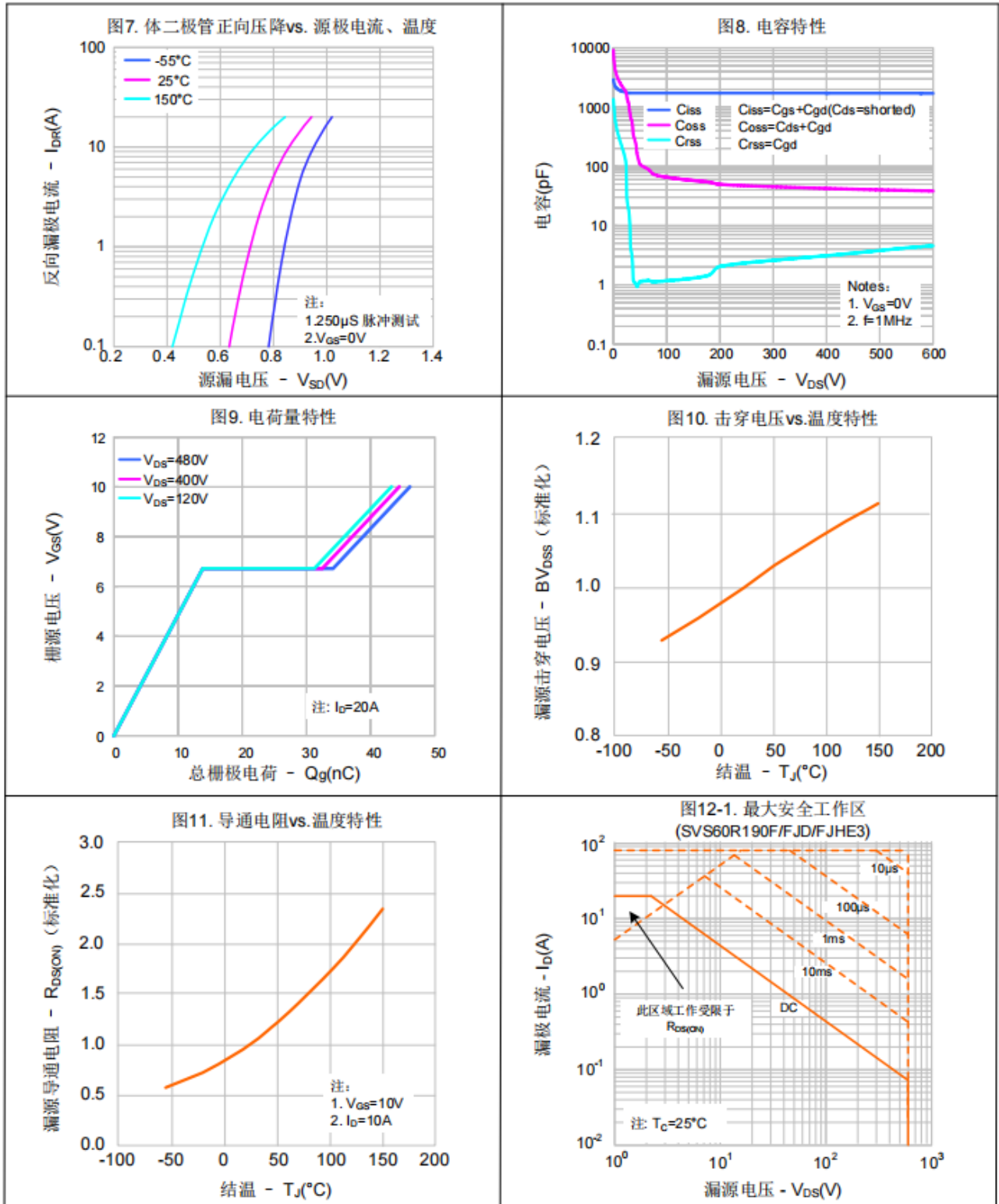


Typical Characteristics



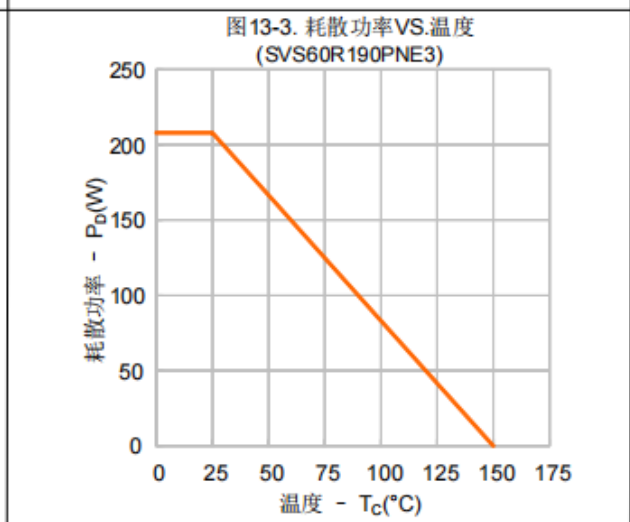
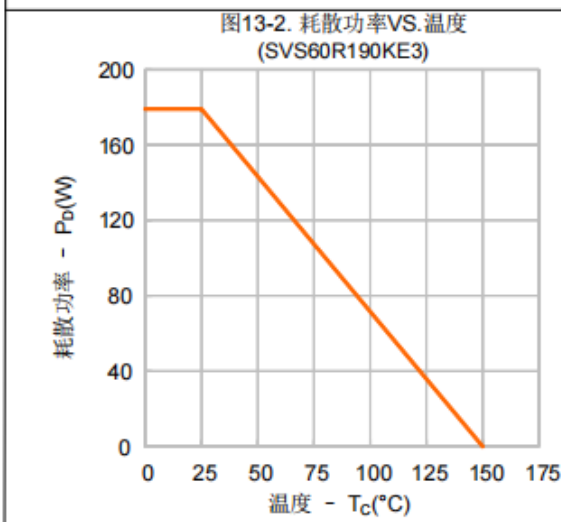
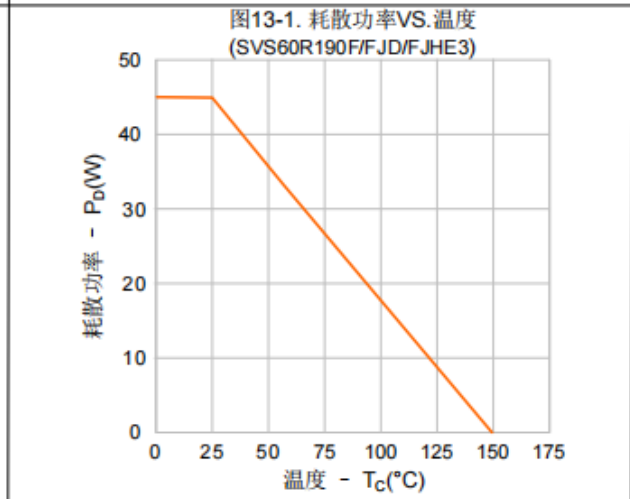
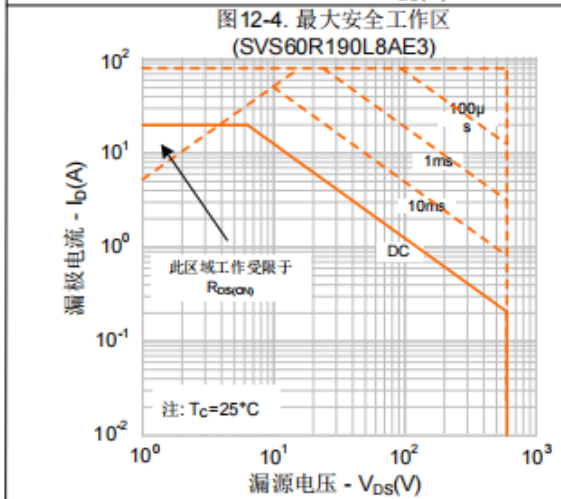
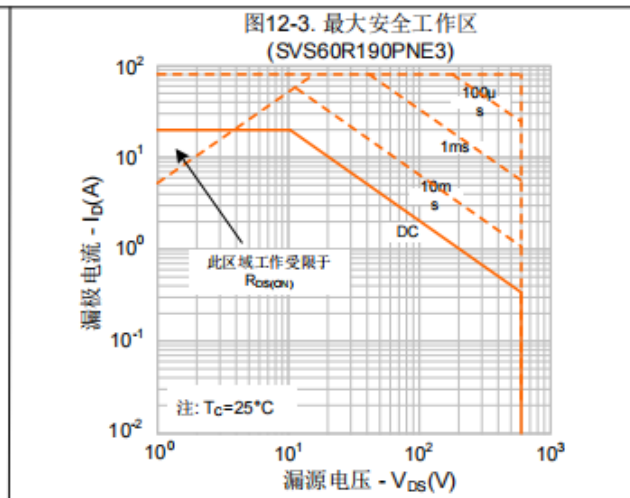
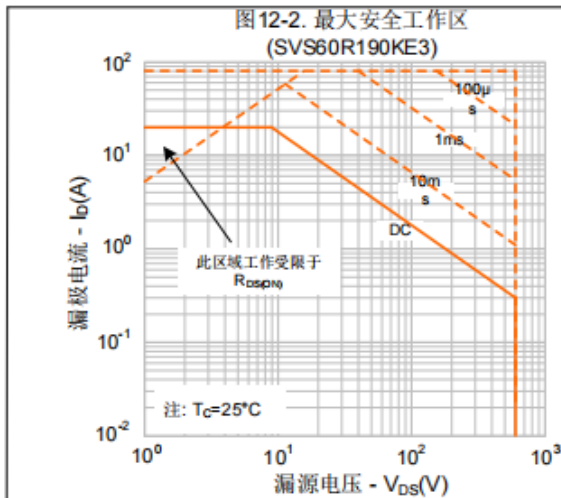


Typical Characteristics(Cont.)



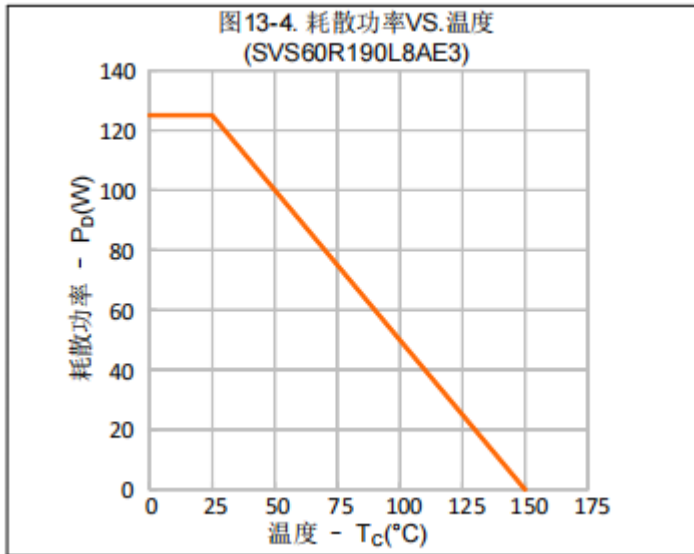


Typical Characteristics(Cont.)





Typical Characteristics(Cont.)





Test Circuits and Waveforms

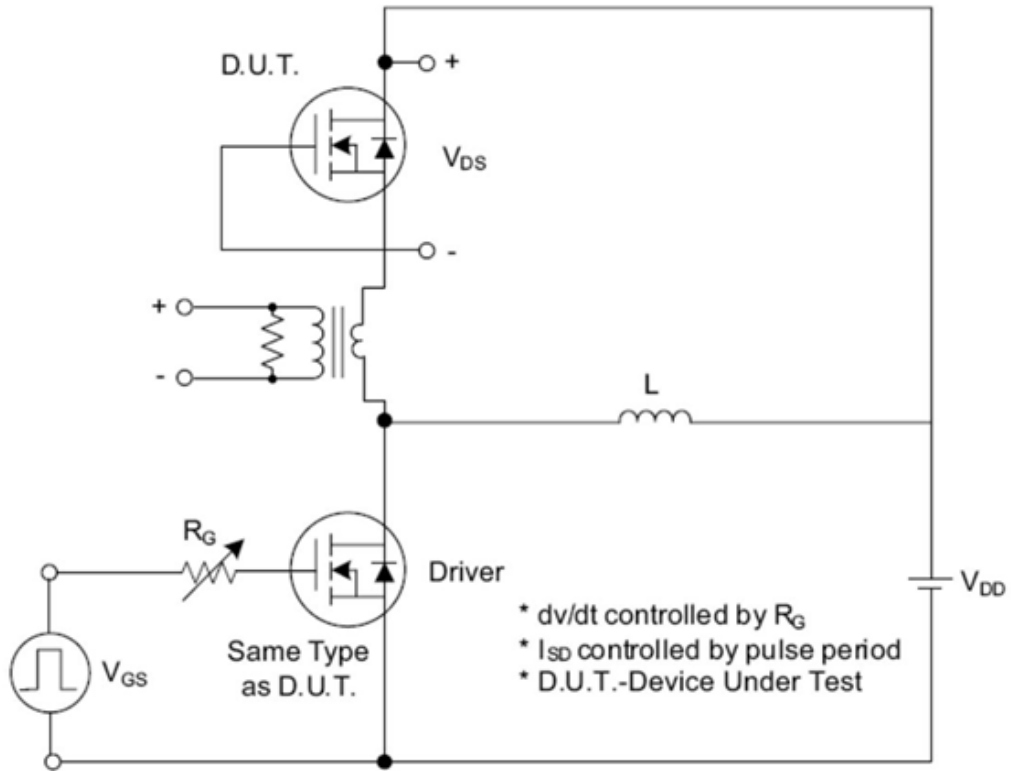


Fig. 1.1 Peak Diode Recovery dv/dt Test Circuit

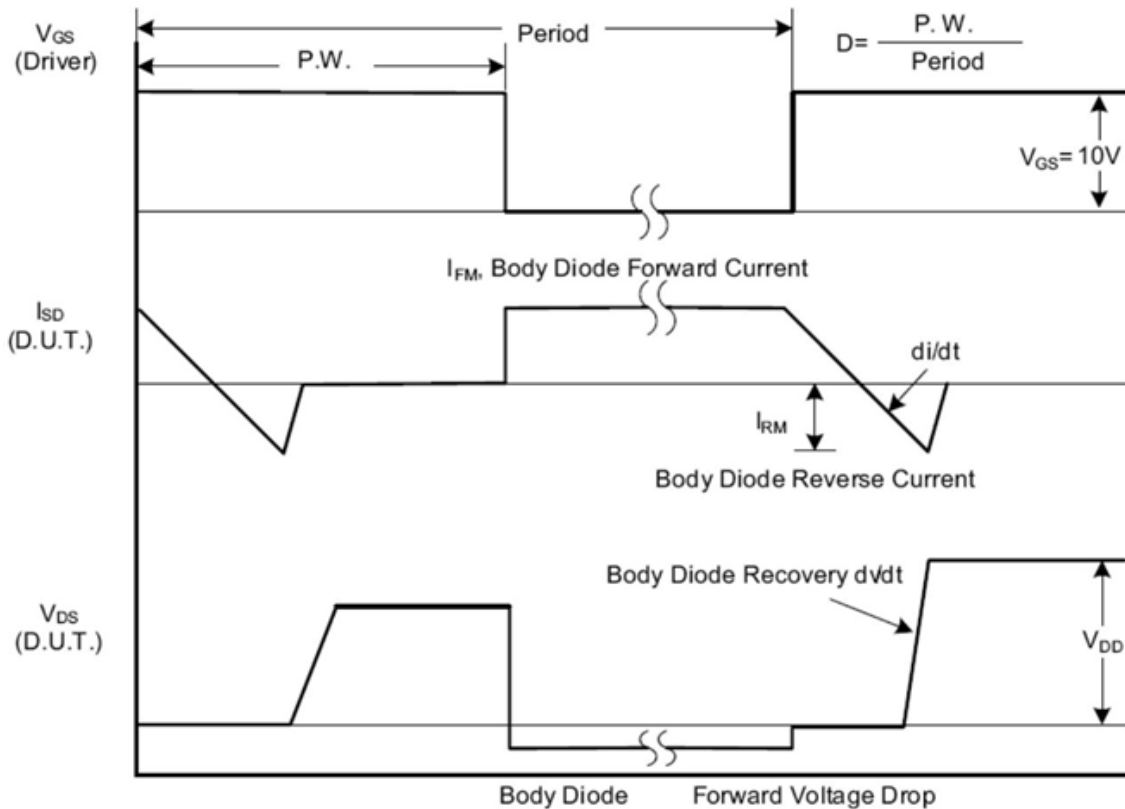


Fig. 1.2 Peak Diode Recovery dv/dt Waveforms



Test Circuits and Waveforms (Cont.)

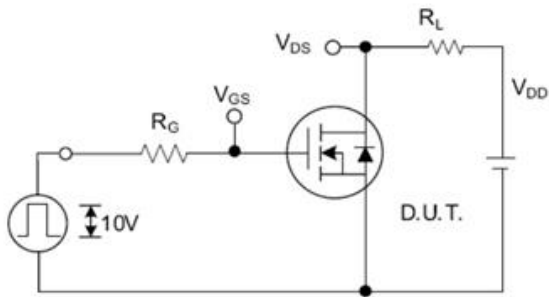


Fig. 2.1 Switching Test Circuit

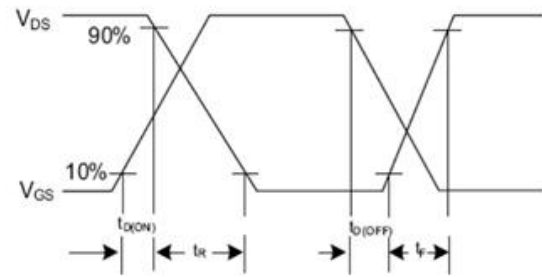


Fig. 2.2 Switching Waveforms

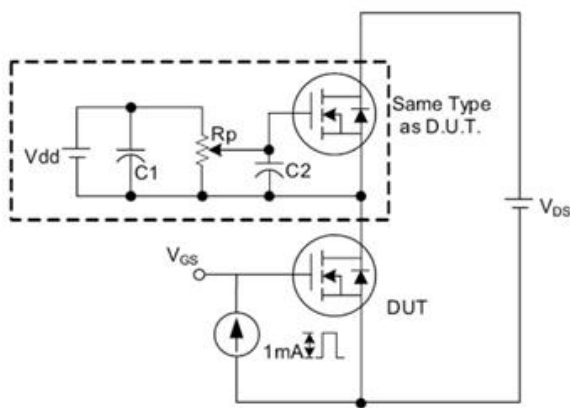


Fig. 3.1 Gate Charge Test Circuit

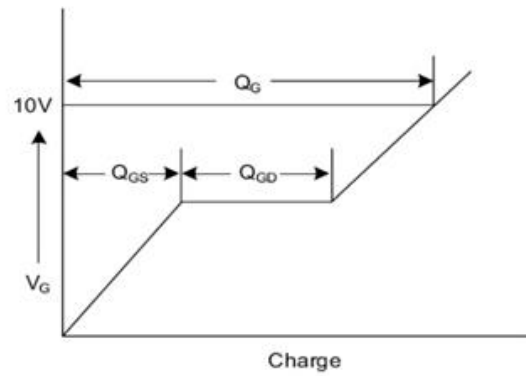


Fig. 3.2 Gate Charge Waveform

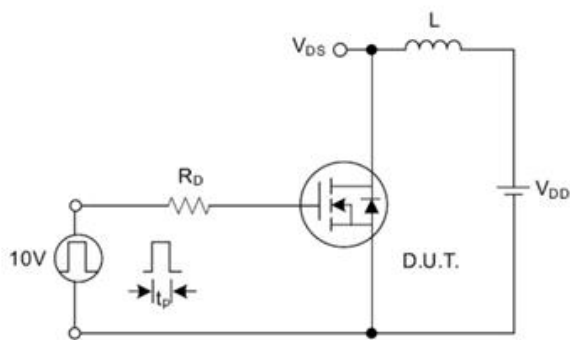


Fig. 4.1 Unclamped Inductive Switching Test Circuit

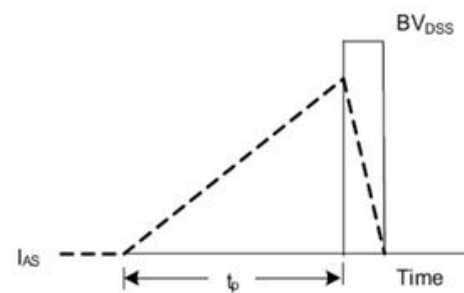


Fig. 4.2 Unclamped Inductive Switching Waveforms